



Date: March 19th, 2014

Engineering Change Notice

ECN #: 1002

Title: MRF555 Bill of Material Changes

Change Category: Requires customer notification & customers are encouraged to evaluate samples prior to placing production orders

In an effort to provide ongoing supply and support of the MRF555 and MRF557 products (complete part number listing below) ASI Semiconductor, Inc has made two changes to the bill of materials:

Change 1: August 2013 the leadframe was altered such that the collector lead width was reduced from min/max of .097/.104 to .033/.039 inches and the length was increased from .348/.383. This change was needed because the previous version of the lead frame could no longer be procured.

Change 2: April 2014 the die was replaced with a new version which is fabricated in a new wafer fab.

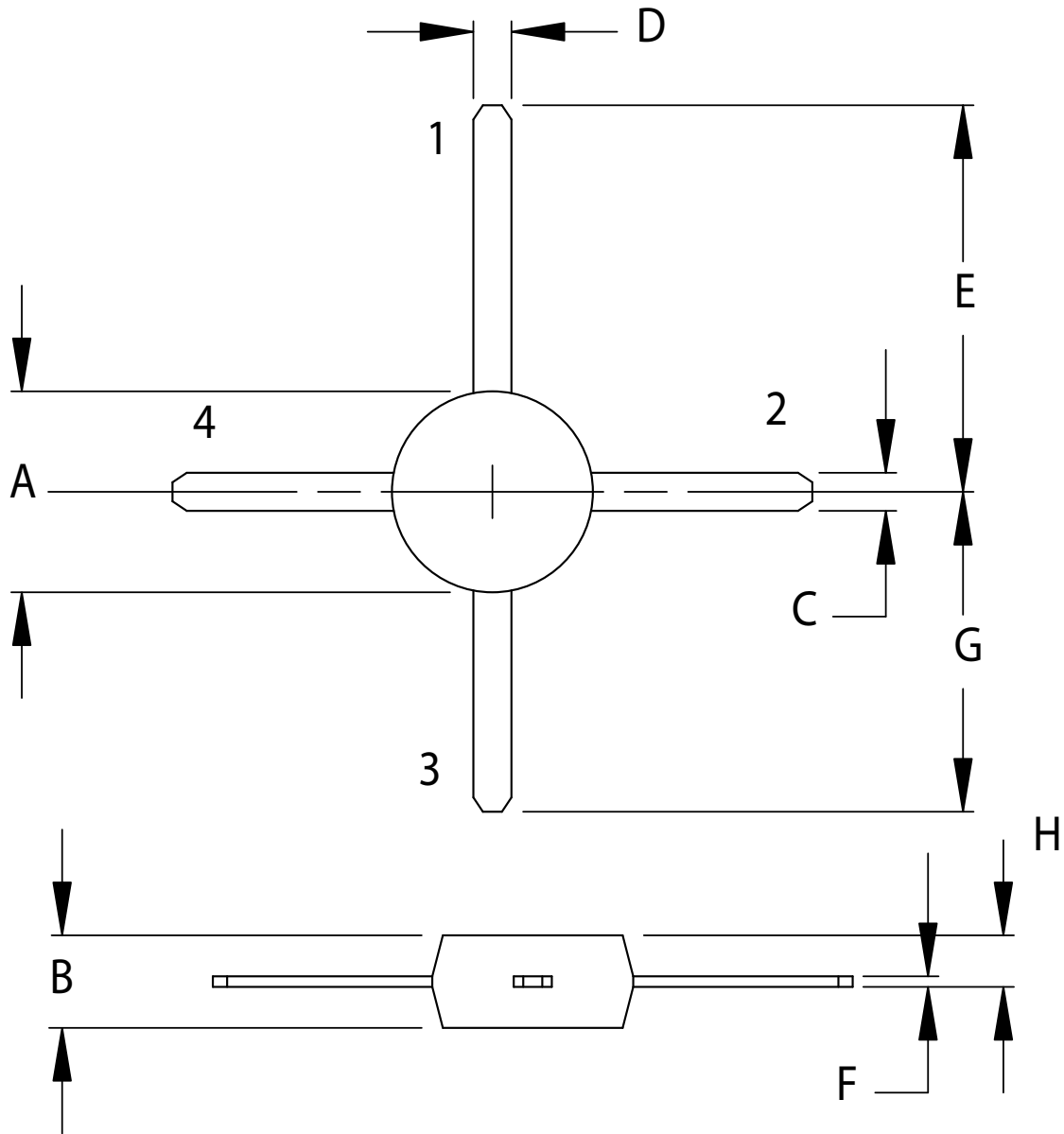
Products Impacted:

MRF555
MRF555T
MRF555LF
MRF555TLF

POWER MACRO

MRF555, MRF555T, MRF557, MRF557T, MRF553, MRF553T

NOTE: AUGUST 2013 LEAD #1 WIDTH WAS REDUCED AND THE LENGTH INCREASED, DIMENSIONS ARE NOW AS SHOWN IN THIS DRAWING



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.45	5.21	.175	.205
B	1.91	2.54	.075	.100
C	0.84	0.99	.033	.039
D	0.84	0.99	.033	.039
E	8.84	9.73	.348	.383
F	0.20	0.31	.008	.012
G	7.24	8.13	.285	.320
H	0.64	1.02	.025	.040